

WHAT IS CLAIMED IS:

1. A method of manufacturing an electronic part in which that side of an insulating member sandwiched between conductor film and a lower conductor layer 5 which is adjacent to said conductor film, a conductor portion connected from said lower conductor layer is exposed, comprising

forming an opening portion having said lower conductor layer as a bottom in the formed area of 10 said conductor portion from said conductor film side,

growing metal plating layer from the bottom of said opening portion with said lower conductor layer as an electrode,

growing metal plating layer on the upper 15 surfaces of said conductor film and said conductor portion with said conductor film and said conductor portion as electrodes after said metal plating layer has reached said conductor film to thereby form said conductor portion in said opening portion, and 20 forming a thickness enough to form an upper conductor layer.

2. A method of manufacturing an electronic part in which on the upper surface of an insulating member 25 covering a lower conductor layer, a conductor portion connected from said lower conductor layer is exposed, comprising

forming conductor film on the upper surface of said insulating member and protective film formed on a part of said insulating member in a thickness direction, and thereafter forming an opening portion 5 having said lower conductor layer as a bottom in said protective film and said conductor film in the formed area of said conductor portion,

growing metal plating layer from the bottom of said opening portion with said lower conductor layer 10 as an electrode, and

growing metal plating layer on the upper surfaces of said conductor film and said conductor portion with said exposed conductor film and said conductor portion on which protective film is not 15 formed as electrodes, to thereby form a thickness enough to form an upper conductor layer after said metal plating layer has reached said conductor film to thereby form said conductor portion in said opening portion.

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3. A method according to Claim 1 or 2, wherein said exposed conductor film providing said electrode is set outside a product area.

25 4. A method according to Claim 1 or 2, wherein said insulating member and said conductor film are made integral with each other in advance.

5. An electronic part having structure in which an upper conductor layer is formed on the upper surface of an insulating member covering a lower conductor layer, and
- 10        said lower conductor layer and said upper conductor layer are connected together by a conductor portion extending through said insulating member, wherein said conductor portion forming the connection between said lower conductor layer and said upper conductor layer, and an upper predetermined thickness in said upper conductor layer are formed by only the precipitation of a metal by electroplating.